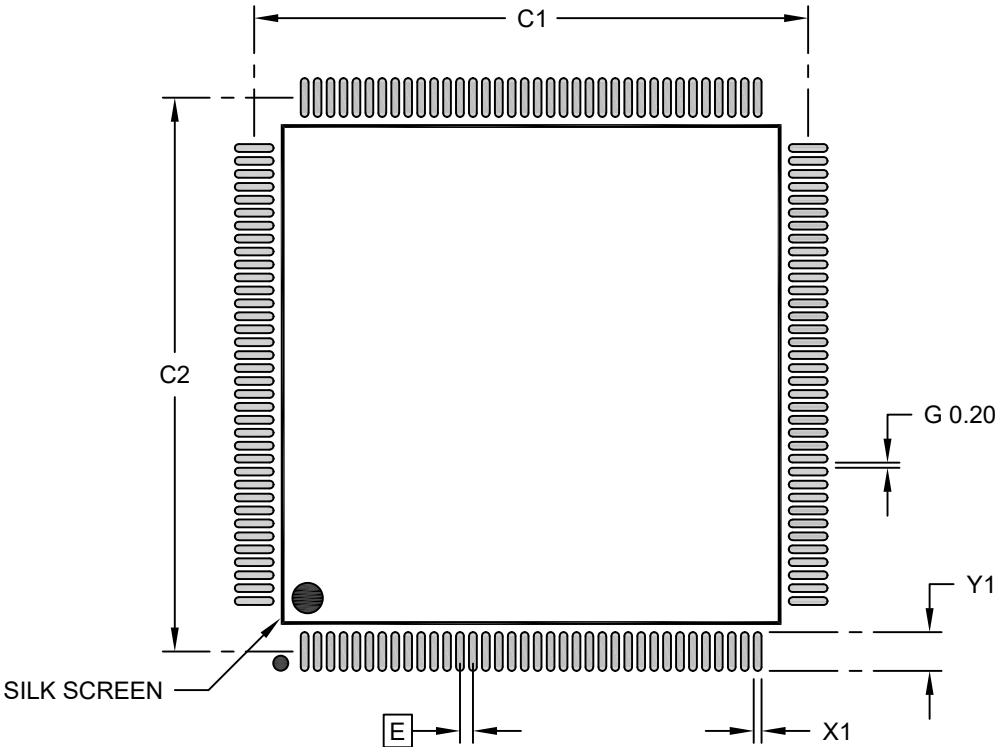


144-Lead Plastic Thin Quad Flat Pack (Z8X) - 20x20x1.0 mm Body [TQFP]
SMSC Legacy Package VTQE3

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		21.40	
Contact Pad Spacing	C2		21.40	
Contact Pad Width (Xnn)	X1			0.30
Contact Pad Length (Xnn)	Y1			1.50
Contact Pad to Contact Pad (Xnn)	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.